



Physical Interfaces & Carriers Japan TC Chapter

Meeting Summary and Minutes

Japan Autumn Meetings 2024

Monday, September 2, 2024, 13:00-15:00 (JST)

SEMI Japan office (via OVTCCM) Hybrid

TC Chapter Announcements

Next TC Chapter Meeting

Thursday 9:00-12:00, December 12, 2024 (Japan Standard Time) at Room702 7F Int'l Conference Tower, Tokyo Big Sight + OVTCCM during SEMICON Japan 2024

Table 1 Meeting Attendees

Italics indicate virtual participants

Co-Chairs: Tsuyoshi Nagashima (Miraial), Daisuke Sado (DAIHEN), Shoji Komatsu (Acteon), Yasuhisa Ito (Murata Machinery)

SEMI Staff: Hirofumi Kanno

<i>Company</i>	<i>First</i>	<i>Last</i>	<i>Company</i>	<i>First</i>	<i>Last</i>
Acteon NEXT LLC	Shoji	Komatsu	<i>Miraial Co., Ltd.</i>	<i>Tsuyoshi</i>	<i>Nagashima</i>
DAIHEN Corporation	Daisuke	Sado	MURATA MACHINERY, LTD.	Yasuhisa	Ito
<i>KOKUSAI ELECTRIC CORPORATION</i>	<i>Mitsuhiro</i>	<i>Matsuda</i>	Shin-Etsu Polymer Co., Ltd.	Satoshi	Odashima
SINFONIA TECHNOLOGY CO., LTD.	Yasushi	Taniyama	SINFONIA TECHNOLOGY CO., LTD.	Taisuke	Matsukubo
Hirata Corporation	Keiji	Kanazawa	<i>Hirata Corporation</i>	<i>Noriyoshi</i>	<i>Toyoda</i>
SCREEN Semiconductor Solutions Co., Ltd.	Takayuki	Nishimura	TOKYO SEIMITSU CO., LTD.	Naomune	Taniguchi
TDK Corporation	Tsutomu	Okabe	<i>TDK Corporation</i>	<i>Kiyoshi</i>	<i>Kanashiro</i>
DAIFUKU CO, LTD.	Tomoko	Suzuki	SEMI Japan	Hirofumi	Kanno

Table 2 Leadership Changes

<i>WG/TF/SC/TC Name</i>	<i>Previous Leader</i>	<i>New Leader</i>
None		

Table 3 TC Chapter Structure Changes

<i>Previous WG/TF/SC Name</i>	<i>New WG/TF/SC Name or Status Change</i>
None	

Table 4 Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
None		



#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Ratification Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>ISC A&R Action</i>	<i>A&R Forms</i>
None			

Note 1: **Passed** Ratification ballots will be submitted to SEMI publication for final processing.

Note 2: **Failed** Ratification ballots were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 6 Activities Approved by the GCS between meetings of the TC Chapter

<i>#</i>	<i>Type</i>	<i>SC/TF/WG</i>	<i>Details</i>
None			

Table 7 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

<i>#</i>	<i>Type</i>	<i>SC/TF/WG</i>	<i>Details</i>
7290	SNARF	Panel Level Packaging (PLP) Panel FOUN Task Force	Line Item Revision to SEMI E182-0424 - Specification for Panel FOUN Loadport for Panel Level Packaging

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:

<http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF>

Table 8 Authorized Ballots

<i>#</i>	<i>When</i>	<i>TF</i>	<i>Details</i>
7290	Cycle 8, 2024	Panel Level Packaging (PLP) Panel FOUN Task Force	Line Item Revision to SEMI E182-0424 - Specification for Panel FOUN Loadport for Panel Level Packaging

Table 9 SNARF(s) Granted a One-Year Extension

<i>#</i>	<i>TF</i>	<i>Title</i>	<i>Expiration Date</i>
None			

Table 10 SNARF(s) Cancelled

<i>#</i>	<i>TF</i>	<i>Title</i>
None		

Table 11 Standard(s) to receive Inactive Status

<i>Standard Designation</i>	<i>Title</i>
None	

Table 12 New Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20240902-1	SEMI Japan	There is concerned that not many people will be able to attend the Global Standards Summit (GSS) all day. One idea is that if it is possible to categorise each topics, that should be coordinated with the time of the Task Force. SEMI Japan staff will suggest to the GSS Preparatory team.
20240902-2	SEMI Japan	Since PIP appreciation issued by E182 revision was received, SEMI Japan will obtain the PIP document and request approval to the Publication Manager and PIC TC Co-chair
20240902-3	Shoji Komatsu, Acteon NEXT LLC	There is reported that sometimes no Roster in the TF meeting. Mr. Shoji Komatsu will notice the appropriate operations to TF leaders in the next meeting.

Table 13 Previous Meeting Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20240719-1	PIC Committee Co-Chair	The policy will be to include TF activity reports from other committees if needed in the next PIC Committee agenda. →Done

1 Welcome, Reminders, and Introductions

Yasuhisa Ito (Murata Machinery) called the meeting to order at 13:00. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: 1_Required Meeting Elements March 2024_J

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion:	Approve the minutes
By / 2nd:	Shoji Komatsu, Acteon NEXT LLC / Daisuke Sado, DAIHEN Corporation
Discussion:	None
Vote:	14-Y 0-N Voting Result: Pass - 100.00%. Voting Rule: Majority

Attachment: 2_Previouse PIC Committee Minutes

3 Liaison Reports

3.1 *PI&C North America TC Chapter*

SEMI Japan Staff has omitted the presentation on the Liaison report, as it is the same material as last time.

Attachment: 3_NA PIC Liaison Report July2024 v2

3.2 *SEMI Staff Report*

Hirofumi Kanno (SEMI Japan) gave the SEMI Staff Report.

Attachment: 4_Staff Report July 2024 v4

4 Ballot Review

None

5 Subcommittee and Task Force Reports

5.1 Global PIC Standards Maintenance TF

No reportable matters.

5.2 Japan Electron Microscopy Workflow liaison TF

No reportable matters.

5.3 Panel Level Packaging Panel FOUP TF

Shoji Komatsu reported based on the attached slides.

Attachment: 5_Panel FOUP TF report_20240902

5.4 Next Gen Assembly / Test Material Handling TF

No reportable matters.

5.5 [Liaison: 3D Packaging & Integration JA TC Chapter] Panel Level Packaging Glass Carrier TF

No reportable matters.

5.6 [Liaison: 3D Packaging & Integration NA TC Chapter] Panel Level Packaging Panel TF

No reportable matters.

6 Old Business

6.1 Project Period Review

None.

6.2 5 Year Review

None.

7 New Business

7.1 SEMICON Japan Schedule (TC & Task Force)

Hirofumi Kanno from Semi Staff shared a schedule proposal of PIC Committee related meeting held on SEMICON Japan.

Action Item 20240902-1: There is concerned that not many people will be able to attend the Global Standards Summit (GSS) all day. One idea is that if it is possible to categorise each topics, that should be coordinated with the time of the Task Force. SEMI Japan staff will suggest to the GSS Preparatory team.

7.2 Require approvals SNARF and Ballot regarding E182

Approved the SNARF for Line Item Revision to SEMI E182-0424 - Specification for Panel FOUP Loadport for Panel Level Packaging

Motion:	Approved the SNARF for Line Item Revision to SEMI E182-0424 - Specification for Panel FOUP Loadport for Panel Level Packaging
By / 2nd:	Shoji Komatsu, Acteon NEXT LLC / Daisuke Sado, DAIHEN Corporation
Discussion:	None
Vote:	14-Y 0-N Voting Result: Pass - 100.00%. Voting Rule: Majority



Motion:	Authorize the Document for Line Item Revision to SEMI E182-0424 - Specification for Panel FOUP Loadport for Panel Level Packaging on Cycle 8, 2024
By / 2nd:	Shoji Komatsu, Acteon NEXT LLC / Daisuke Sado, DAIHEN Corporation
Discussion:	None
Vote:	14-Y 0-N Voting Result: Pass - 100.00%. Voting Rule: Majority

Publication Improvement Proposal (PIP) related to E182-0424 currently issued by Shoji Komatsu was suggested, however it found that it is required to the approval of PIC committee chair and Semi Publication Manager in addition to this procedure.

Action Item 20240902-2: Semi Japan staff will Obtain the PIP document and request for the PIP document and approval to the Publication Manager and PIC TC Co-chair.

Attachment: 5_Panel FOUP TF report_20240902 / 6_7290, SEMI Publication Improvement Proposal (PIP) Form

Action Item 20240902-3: There is reported that sometimes no Roster in the TF meeting. Shoji Komatsu will notice the appropriate operations to TF leaders in the next meeting.

8 Next Meeting and Adjournment

Thursday 9:00-12:00, December 12, 2024 (Japan Standard Time) at Room702 7F Int'l Conference Tower, Tokyo Big Sight + OVTCCM during SEMICON Japan 2024

See <http://www.semi.org/standards-events> for the current list of events.

Adjournment: 15:00

Respectfully submitted by:

Hirofumi Kanno

Sir Manger, Standards & EHS

SEMI Japan

Email: hkanno@semi.org

Minutes tentatively approved by:

Tsuyoshi Nagashima (Miraial)	September 27th, 2024
Daisuke Sado (DAIHEN)	September 11th, 2024
Yasuhisa Ito (MURATA MACHINERY)	September 27th, 2024

Table 14 Index of Available Attachments^{#1}

<i>Title</i>	<i>Title</i>
1_Required Meeting Elements March 2024_J	2_PIC Mins v0.1 08062024
3_NA PIC Liaison Report July2024 v2	4_Staff Report July 2024 v4
5_Panel FOUP TF report_20240902	6_SEMI Publication Improvement Proposal (PIP) Form

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.